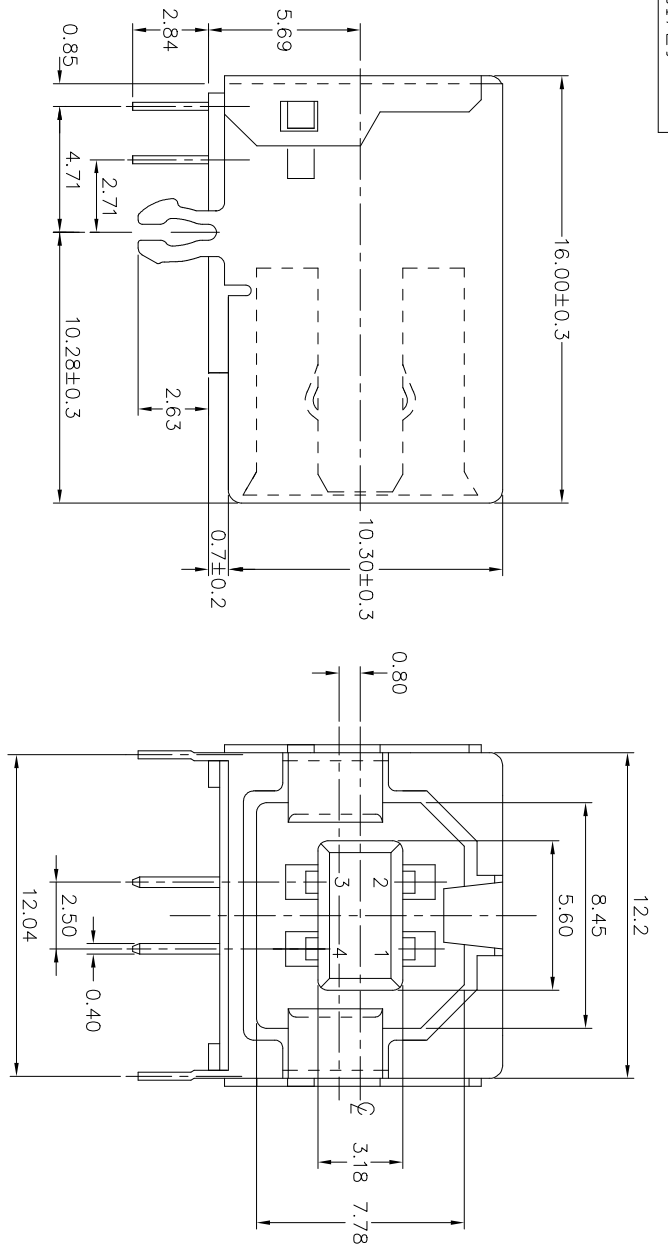
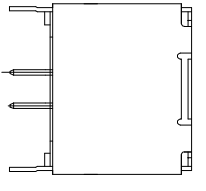


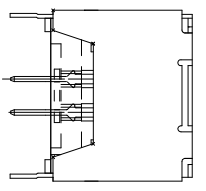
PRODUCT NO.  
61729-\*



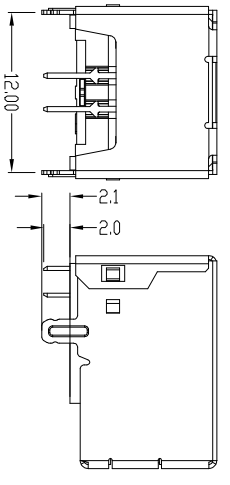
TYPE"1" FULL BACK



TYPE"2" PARTIAL BACK



TYPE"3" PARTIAL BACK WITH SHORT SOLDER TAIL AND SHELL TAIL FOR PIP PROCESS 61729-XXQXLF



PRODUCT NUMBER CODE:

61729 - X X X X X P S LF

BASE PRODUCT NUMBER

HOUSING COLOR OPTION

0 - WHITE  
1 - BLACK

HALOGEN OPTION

0 - WITH HALOGEN  
1 - HF (HALOGEN FREE)

SHIELD OPTION

1 - FULL BACK  
2 - PARTIAL BACK

3 - FULL BACK (SPECIAL PLATING IN ONLY)  
S - FULL BACK (SPECIAL MATERIAL FOR 12,000 DURABILITY CYCLES)

P - PARTIAL BACK (SPECIAL MATERIAL FOR 12,000 DURABILITY CYCLES)

Q - PARTIAL BACK WITH SHORT TAIL FOR TYPE 3

TERMINAL PLATING OPTION

0 - 50u" NI UNDERPLATED  
30u" GXT CONTACT AREA

100u" PURE TIN TAIL AREA

1 - 50u" NI UNDERPLATED  
30u" GOLD OR 30u" GXT CONTACT AREA

100u" PURE TIN TAIL AREA

2 - 50u" NI UNDERPLATED  
GOLD FLASH CONTACT AREA

100u" PURE TIN TAIL AREA

3 - 50u" NI UNDERPLATED  
30u" GOLD CONTACT AREA

100u" PURE TIN TAIL AREA

PACKAGING OPTION

B - TUBES

R - TAPE & REEL

DATE CODE OPTION

P - WITH DATE CODE

DEFAULT: WITHOUT DATE CODE

ONLY FOR PANSONIC

LEAD FREE OPTION

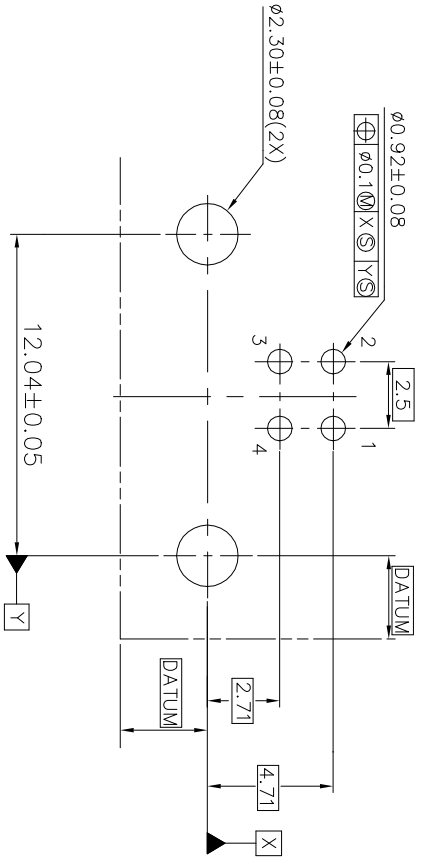
mat'l. code	ecn no	dr	date	surface	tolerance	projection	product family
S	N05-0242	PH	08/22/05	ISO 1302	ISO 406	ISO 1108	HPL 511 USB2.0
T	N06-0103	HB	04/15/06	tolerances unless otherwise specified	0.0±0.30	1108	
U	N08-0238	RB	11/03/08	0±±2"	0.00±0.20	mm	
V	N08-0246	RB	12/08/08	Yuan-Yuan Bco	0.000±0.10	scale 1:1	
W	ER-N-16533	LQ	12/17/13	engr Yuan-Yuan Bco			
X	ER-N-29556	LZ	03/09/18	chr Tim.Yao			
Y	ER-N-32780	YY	02/26/19	ppd Tim.Yao			
sheet index	revision	sheet					

USB RECEPTACLE B TYPE

dwg no 61729

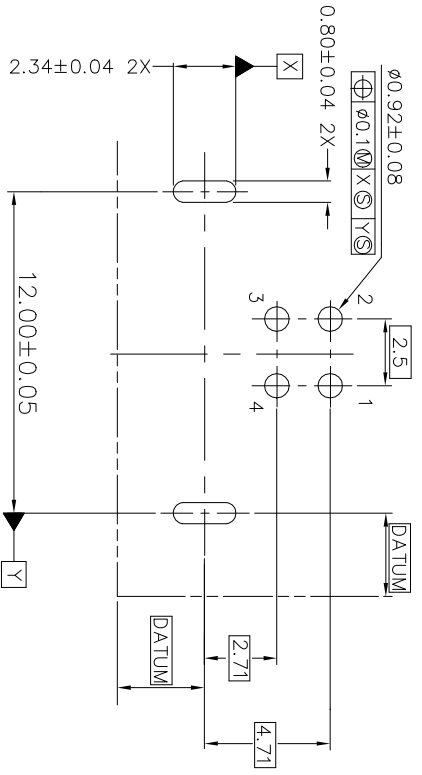
sheet 1 of 2 size A3

type Product Customer Drawing



P.C. BOARD LAYOUT

STYLE 1 APPLY FOR TYPE 1 & 2



P.C. BOARD LAYOUT

STYLE 2 APPLY FOR TYPE 3

NOTES:

1. MATERIAL:  
SHIELD & CONTACTS: COPPER ALLOY  
HOUSING: UL 94V-0 ,HIGH TEMPERATURE THERMOPLASTIC.  
COLOR: SEE PRODUCT NUMBER CODE.
2. PLATING: SEE PRODUCT NUMBER CODE.  
SHIELD: BRIGHT TIN, NICKEL UNDERPLATE(USED FOR WAVE SOLDER PROCESS),  
PLATING NICKEL ONLY(USED FOR PIP PROCESS).
3. DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER
4. RECOMMENDED BOARD THICKNESS IS 1.57 mm (.062)
5. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD FREE P/N'S
6. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008
7. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRO-RED OR VAPOR PHASE REFLOW OVEN.
8. THE PART CAN BE USED FOR PIP PROCESS.



mat'l. code	surface	tolerance	projection	product family
ISO 1302	ISO 406	ISO 1101	HPL 511	USB2.0
tolerances unless otherwise specified	0.04±0.30	0.00±0.20	1101	USB RECEPTACLE B TYPE
angles:	0.00±0.20	0.000±0.10	mm	
0±2°	0.000±0.10	scale 1:1		
dr	Lawrence,Zang	02/26/19		dwg no
enq	Lawrence,Zang	02/26/19		sheet 2 of 2
chr	Tim.Yao	02/26/19		size
qppd	Tim.Yao	02/26/19		A3
sheet	revision			type
index	sheet			Product Customer Drawing